

ABSTRACT

Methods for processing at least one die which comprises an integrated circuit. In one example of a method of the invention, an identification code is applied to a carrier. A singulated die is deposited into the carrier which
5 holds the singulated die. The singulated die comprises an integrated circuit. The identification code may be applied to the carrier before or after depositing the singulated die into the carrier. The carrier may be used in testing the singulated die and may include a plurality of singulated die or just one singulated die. In another example of a method of the invention, an
10 identification code is applied to a die. The die is deposited into a carrier which holds the die. The die comprises an integrated circuit, and the carrier holds the die in singulated form. Typically the die is placed in the carrier without any packaging which may protect the die. The identification code may be applied to the die before or after it is deposited into the carrier.